



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP 60 H6327		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001219564						
<b>Package</b>		PG-SOT223-4-24		<b>Weight*</b>		107.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.00		27	
	noble metal	gold	7440-57-5	0.011	0.01		105	
	inorganic material	silicon	7440-21-3	0.137	0.13	0.14	1278	1410
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		80	
	non noble metal	titanium	7440-32-6	0.043	0.04		398	
	non noble metal	chromium	7440-47-3	0.128	0.12		1193	
	non noble metal	copper	7440-50-8	42.459	39.61	39.78	396141	397812
wire	non noble metal	copper	7440-50-8	0.082	0.08	0.08	766	766
encapsulation	organic material	carbon black	1333-86-4	0.624	0.58		5817	
	plastics	epoxy resin	-	9.353	8.73		87261	
	inorganic material	silicondioxide	60676-86-0	52.375	48.86	58.17	488660	581738
leadfinish	non noble metal	tin	7440-31-5	1.464	1.37	1.37	13659	13659
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4615	4615
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com